

**ABS2 THRU ABS10**  
**SINGLE PHASE GLASS PASSIVATED BRIDGE RECTIFIERS**  
Voltage Range - 200 to 1000 Volts Current - 0.8/1.0 Ampere

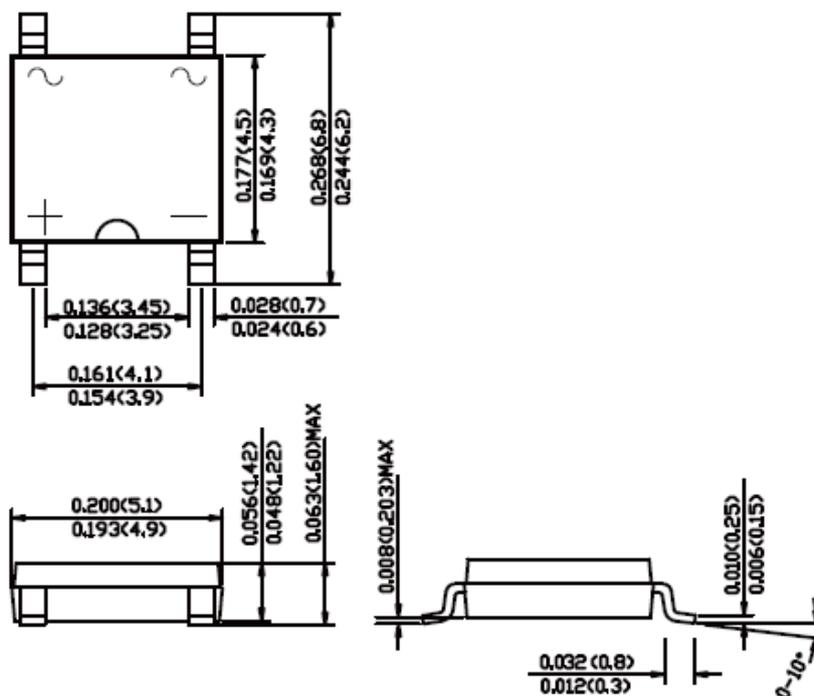
**Features:**

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260 /10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability
- Glass passivated chip junction

**Mechanical Data:**

- Case: Molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbols marked on case
- Mounting Position: Any

**Mechanical Dimensions: In Inches/mm**



**ABS**

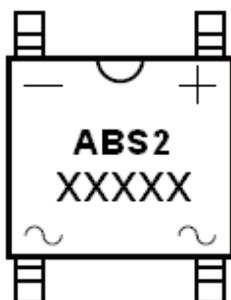


# ABS2 THRU ABS10

Technical Data  
Data Sheet N1693, Rev. -

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## Marking Diagram:



Where XXXXX is YYWWL

ABS2 = Part Name  
YY = Year  
WW = Week  
L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

## Ordering Information:

Device	Package	Shipping
ABS2 THRU ABS10	ABS (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.



**Maximum Ratings and Electrical Characteristics**

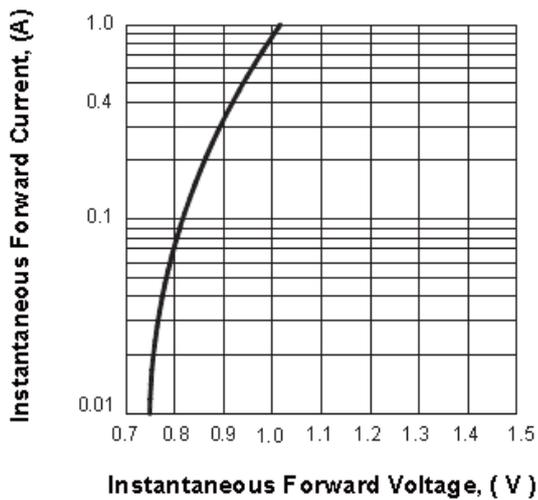
Rating at 25°C ambient temperature unless otherwise specified

Single Phase half wave 60Hz, resistive or inductive load. For capacitive load current derate by 20%.

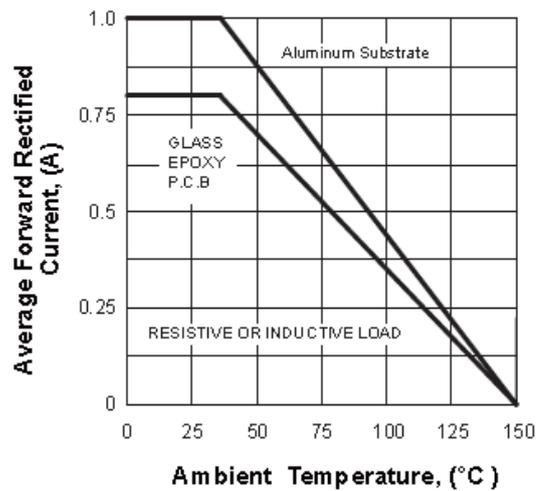
Characteristic	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	Units
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	140	280	420	560	700	
Maximum DC blocking voltage	$V_{DC}$	200	400	600	800	1000	
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{(AV)}$	0.8 1.0					V
Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30					A
Maximum instantaneous forward voltage drop per leg at 0.4A	$V_F$	0.95					V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ C$ $T_A = 100^\circ C$	$I_R$	5 100					$\mu A$
Typical thermal resistance (Note 3)	$R_{\theta JL}$ $R_{\theta JA}$	25 80					$^\circ C/W$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150					$^\circ C$

- Note:** 1. On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads  
 2. On aluminum substrate P.C.B. with on area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad  
 3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

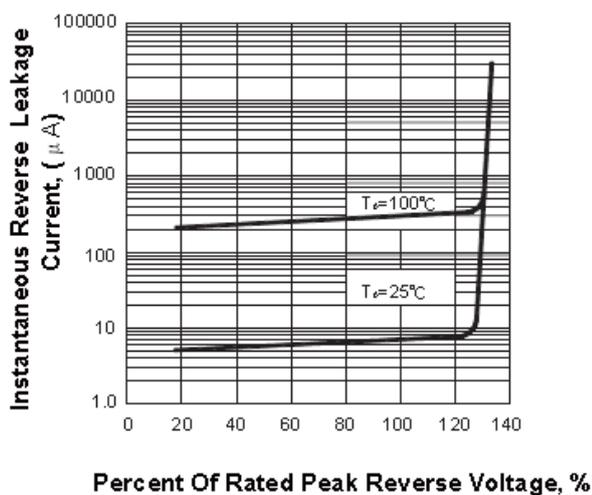
**FIG.1 TYPICAL FORWARD CHARACTERISTICS**



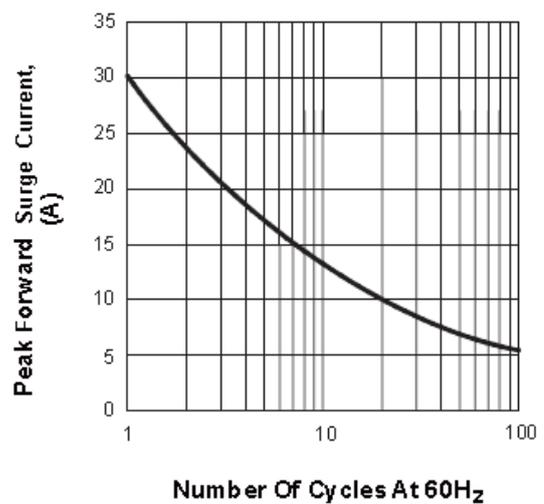
**FIG.2 FORWARD DERATING CURVE**



**FIG.3 TYPICAL REVERSE CHARACTERISTICS**



**FIG.4 PEAK FORWARD SURGE CURRENT**





**ABS2  
THRU  
ABS10**

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